



COMPLEMENTARY PAIR ENHANCEMENT MODE MOSFET

Product Summary

Device	BV _{DSS}	R _{DS(ON)} max	I _D Max T _A = +25°C
Q2	30V 21mΩ @ V _{GS} = 10V		8.5A
Q2 30V	$32m\Omega$ @ $V_{GS} = 4.5V$	7.2A	
04 001/		$39m\Omega$ @ $V_{GS} = -10V$	-7A
Q1	-30V	$53m\Omega$ @ $V_{GS} = -4.5V$	-5.6A

Description

This MOSFET has been designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

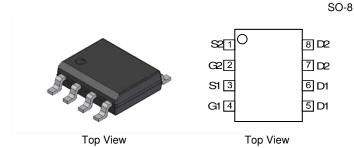
- Power Management Functions
- Analog Switch
- Load Switch

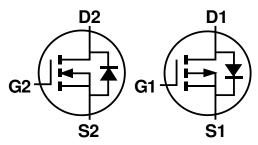
Features

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Complementary Pair MOSFET
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Q-suffix) part. A listing can be found at
 - https://www.diodes.com/products/automotive/automotive-products/.
- This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability. https://www.diodes.com/quality/product-definitions/
- An Automotive-Compliant Part is Available Under Separate Datasheet (DMC3021LSDQ)

Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Lead Frame. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.072 grams (Approximate)





N-Channel MOSFET

P-Channel MOSFET

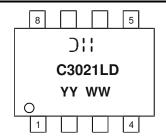
Ordering Information (Note 4)

Part Number	Case	Packaging	
DMC3021LSD-13	SO-8	2500/Tape & Reel	

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



O'!| = Manufacturer's Marking
C3021LD = Product Type Marking Code
YYWW = Date Code Marking
YY or YY = Year (ex: 20 = 2020)
WW = Week (01 to 53)



Maximum Ratings N-CHANNEL - Q2 (@TA = +25°C, unless otherwise specified.)

Char	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	30	V
Gate-Source Voltage	V _{GSS}	±20	V
Continuous Drain Current (Note 5)	ID	8.5 7.1	А
Pulsed Drain Current (Note 6)	I _{DM}	40	Α

Maximum Ratings P-CHANNEL – Q1 (@TA = +25°C, unless otherwise specified.)

Chai	Symbol	Value	Unit
Drain-Source Voltage	VDSS	-30	V
Gate-Source Voltage	V _{GSS}	±20	V
Continuous Drain Current (Note 5)	ΙD	-7.0 -4.5	А
Pulsed Drain Current (Note 6)	I _{DM}	-30	Α

Thermal Characteristics (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	PD	2.5	W
Thermal Resistance, Junction to Ambient (Note 5)	Reja	50	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

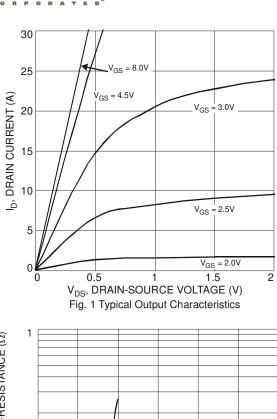
Electrical Characteristics N-CHANNEL - Q2 (@TA = +25°C, unless otherwise specified.)

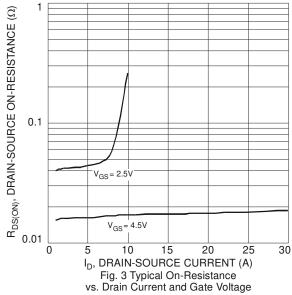
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	30	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current T _J = +25°C	IDSS	_	_	1.0	μΑ	V _{DS} = 30V, V _{GS} = 0V
Gate-Source Leakage	Igss	_	_	±100	nA	$V_{GS} = \pm 20V$, $V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	1	1.45	2.1	V	$V_{DS}=V_{GS},\ I_{D}=250\mu A$
Static Drain-Source On-Resistance	Process	_	14	21	mΩ	$V_{GS} = 10V$, $I_D = 7A$
Static Drain-Source On-Nesistance	RDS(ON)	_	18	32	11122	$V_{GS} = 4.5V, I_{D} = 5.6A$
Forward Transfer Admittance	Y _{fs}	_	8.1	_	S	$V_{DS} = 5V$, $I_D = 7A$
Diode Forward Voltage (Note 7)	V_{SD}	_	0.7	1.0	V	$V_{GS} = 0V, I_{S} = 1A$
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	Ciss	_	767	_	pF	V 40V V 0V
Output Capacitance	Coss	_	110	_	pF	V _{DS} = 10V, V _{GS} = 0V, f = 1.0MHz
Reverse Transfer Capacitance	Crss	_	105	_	pF	1 = 1.0101112
Gate Resistance	Rg	_	1.4	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$
Total Gate Charge (VGS = 4.5V)	Qg	_	7.8	_	nC	
Total Gate Charge (VGS = 10V)	Qg	_	16.1	_	nC	V _{DS} = 15V, I _D = 9A
Gate-Source Charge	Q _{gs}	_	1.8	_	nC	VDS = 15V, ID = 9A
Gate-Drain Charge	Q_{gd}	_	2.5	_	nC	
Turn-On Delay Time	td(on)	_	5.0	_	ns	
Turn-On Rise Time	t _R	_	4.5	_	ns	$V_{GS} = 10V, V_{DS} = 15V,$
Turn-Off Delay Time	tD(OFF)	_	26.3	_	ns	$R_G = 6\Omega$, $I_D = 1A$
Turn-Off Fall Time	tF	_	8.55	_	ns	

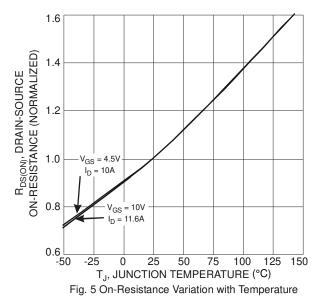
Notes:

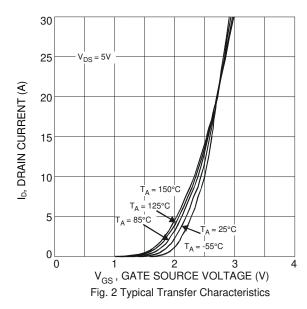
- Device mounted on FR-4 PCB, with minimum recommended pad layout.
 Repetitive rating, pulse width limited by junction temperature.
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to production testing.

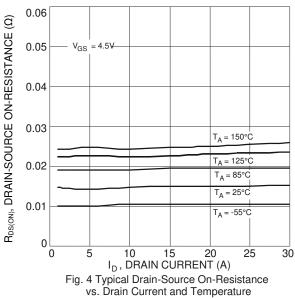












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Fig. 6 On-Resistance Variation with Temperature



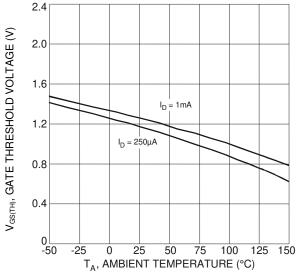
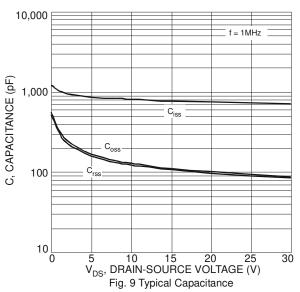
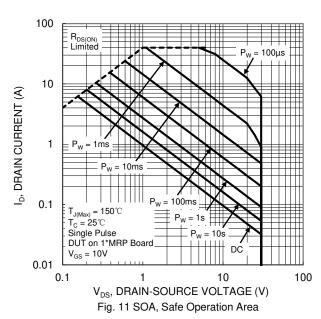
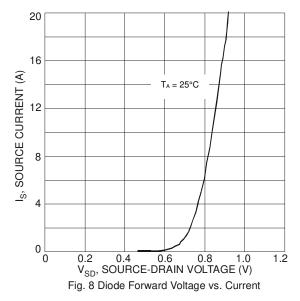


Fig. 7 Gate Threshold Variation vs. Ambient Temperature







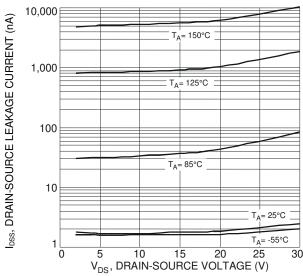


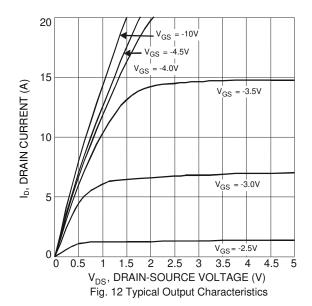
Fig. 10 Typical Drain-Source Leakage Current vs. Drain-Source Voltage

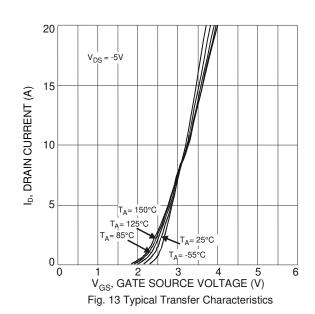


Electrical Characteristics P-CHANNEL - Q1 (@TA = +25°C, unless otherwise specified.)

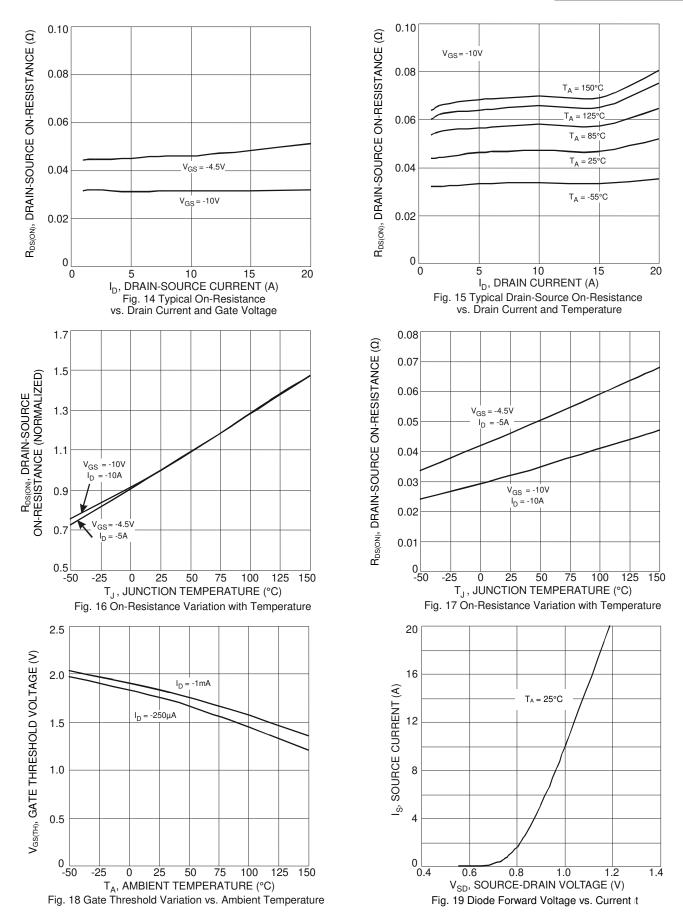
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	-30		_	V	$V_{GS} = 0V, I_{D} = -250\mu A$
Zero Gate Voltage Drain Current T _J = +25°C	IDSS	_	_	-1.0	μΑ	V _{DS} = -30V, V _{GS} = 0V
Gate-Source Leakage	Igss	_	_	±100	nA	$V_{GS} = \pm 20V$, $V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)			•			
Gate Threshold Voltage	V _{GS(TH)}	-1	-1.7	-2.2	V	$V_{DS} = V_{GS}$, $I_D = -250\mu A$
Static Drain-Source On-Resistance	Dagger	_	30	39	mΩ	Vgs = -10V, ID = -4.3A
Static Dialif-Source Off-nesistance	Rds(on)	_	42	53	11122	V _G S = -4.5V, I _D = -3.7A
Forward Transfer Admittance	Y _{fs}	_	7	_	S	$V_{DS} = -5V, I_{D} = -4.3A$
Diode Forward Voltage (Note 7)	V _{SD}	_	-0.75	-1.0	V	V _G S = 0V, I _S = -1.7A
DYNAMIC CHARACTERISTICS (Note 8)			•			
Input Capacitance	Ciss	_	1002	_	pF	101/1/
Output Capacitance	Coss	_	125	_	pF	V _{DS} = -10V, V _{GS} = 0V, -f = 1.0MHz
Reverse Transfer Capacitance	Crss	_	118	_	pF	1 = 1.000112
Gate Resistance	Rg	_	13	_	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz
Total Gate Charge (V _{GS} = -4.5V)	Qg	_	10.1	_	nC	
Total Gate Charge (V _{GS} = -10V)	Qg	_	21.1	_	nC	1577 1 04
Gate-Source Charge	Qgs	_	2.8	_	nC	$V_{DS} = -15V, I_{D} = -6A$
Gate-Drain Charge	Qgd	_	3.2	_	nC	1
Turn-On Delay Time	t _{D(ON)}	_	10.1	_	ns	
Turn-On Rise Time	t _R	_	6.5	_	ns	Vgs = -10V, Vps = -15V,
Turn-Off Delay Time	tD(OFF)	_	50.1	_	ns	$R_G = 6\Omega$, $I_D = -1A$
Turn-Off Fall Time	tF	_	22.2	_	ns	

7. Short duration pulse test used to minimize self-heating effect. 8. Guaranteed by design. Not subject to production testing. Notes:

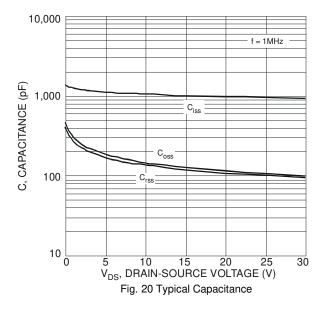


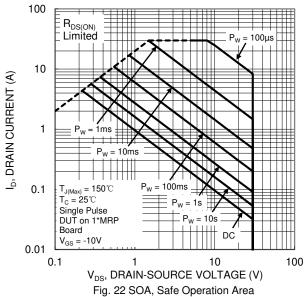


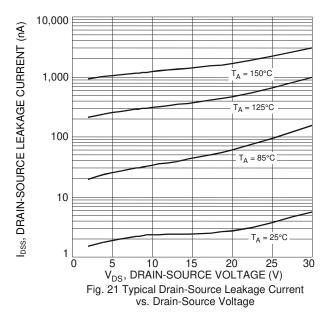










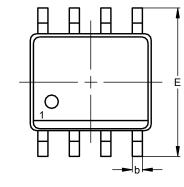


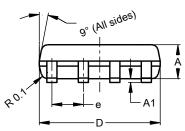


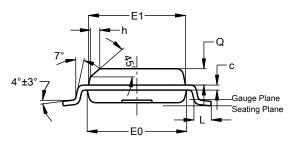
Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8





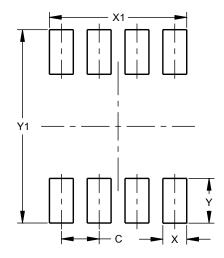


SO-8						
Dim	Min	Max	Тур			
Α	1.40	1.50	1.45			
A 1	0.10	0.20	0.15			
b	0.30	0.50	0.40			
С	0.15	0.25	0.20			
D	4.85	4.95	4.90			
Е	5.90	6.10	6.00			
E1	3.80	3.90	3.85			
E0	3.85	3.95	3.90			
е		-	1.27			
h			0.35			
L	0.62	0.82	0.72			
Q	0.60	0.70	0.65			
All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8



Dimensions	Value (in mm)
С	1.27
X	0.802
X1	4.612
Υ	1.505
Y1	6.50



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